

## **HAT2077R**

# Silicon N Channel MOS FET High Speed Power Switching

REJ03G1179-0200

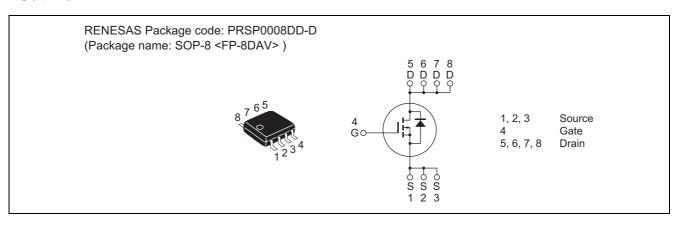
(Previous: ADE-208-1228)

Rev.2.00 Sep 07, 2005

### **Features**

- Low on-resistance
- www.DataSheet&U.Low drive current
  - High density mounting

#### **Outline**



## **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Symbol Value	
Drain to source voltage	V <sub>DSS</sub>	200	V
Gate to source voltage	V <sub>GSS</sub>	±30	V
Drain current	I <sub>D</sub>	3	Α
Drain peak current	I <sub>D (pulse)</sub> Note 1	24	Α
Body-drain diode reverse drain current	I <sub>DR</sub>	3	Α
Channel dissipation	Pch Note 2	2.5	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW  $\leq$  10  $\mu$ s, duty cycle  $\leq$  1%

www.DataSheet4U.com 2. When using the glass epoxy board (FR4  $40 \times 40 \times 1.6$  mm), PW  $\leq 10$  s

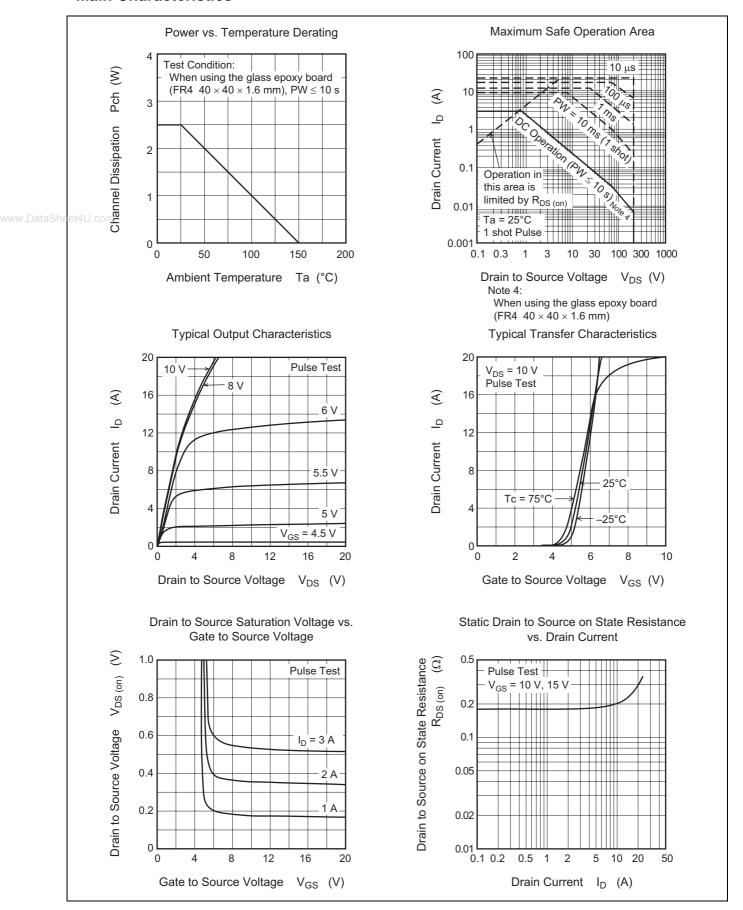
## **Electrical Characteristics**

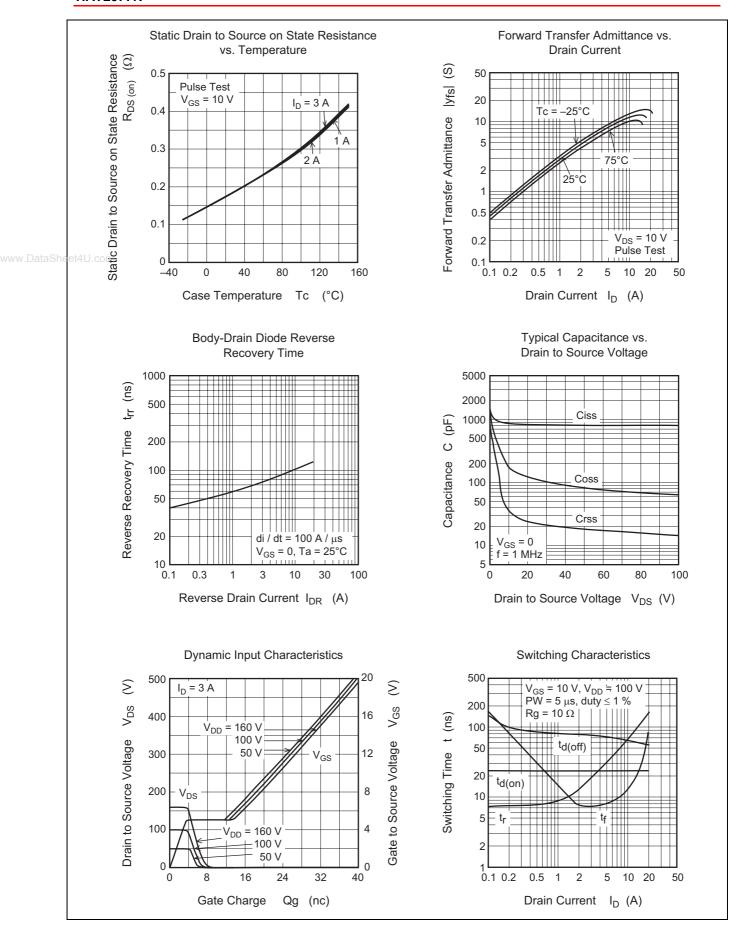
 $(Ta = 25^{\circ}C)$ 

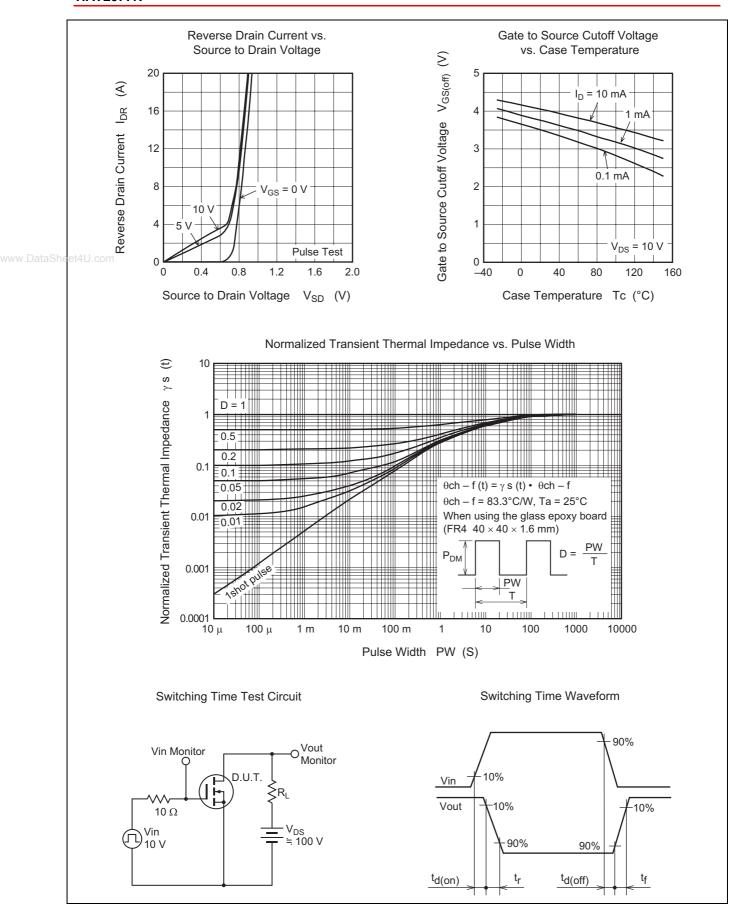
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V <sub>(BR) DSS</sub>	200	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source leak current	I <sub>GSS</sub>	_	_	±0.1	μΑ	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I <sub>DSS</sub>	_	_	1	μΑ	$V_{DS} = 200 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	V <sub>GS (off)</sub>	3.0	_	4.5	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on state resistance	R <sub>DS (on)</sub>	_	0.18	0.235	Ω	$I_D = 1.5 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note 3}}$
Forward transfer admittance	y <sub>fs</sub>	2.3	3.8	_	S	$I_D = 1.5 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note 3}}$
Input capacitance	Ciss	_	830	_	pF	V <sub>DS</sub> = 25 V
Output capacitance	Coss	_	115	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	23	_	pF	f = 1 MHz
Turn-on delay time	t <sub>d (on)</sub>	_	23	_	ns	$V_{DD} \cong 100 \text{ V}, I_D = 1.5 \text{ A}$
Rise time	t <sub>r</sub>	_	10	_	ns	V <sub>GS</sub> = 10 V
Turn-off delay time	t <sub>d (off)</sub>	_	70	_	ns	$R_L = 66.7 \Omega$
Fall time	t <sub>f</sub>	_	10	_	ns	$Rg = 10 \Omega$
Total gate charge	Qg	_	23	_	nC	V <sub>DD</sub> = 160 V
Gate to source charge	Qgs	_	3.5	_	nC	V <sub>GS</sub> = 10 V
Gate to drain charge	Qgd	_	10	_	nC	I <sub>D</sub> = 3 A
Body-drain diode forward voltage	$V_{DF}$	_	0.75	1.15	V	$I_F = 3 \text{ A}, V_{GS} = 0^{\text{Note } 3}$
Body-drain diode reverse recovery time	t <sub>rr</sub>	_	75	_	ns	$I_F = 3 A, V_{GS} = 0$
						di <sub>F</sub> /dt = 100 A/μs

Note: 3. Pulse test

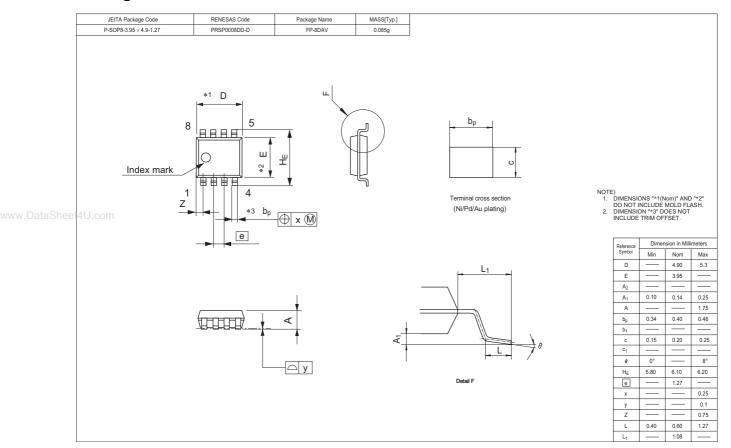
#### **Main Characteristics**







## **Package Dimensions**



## **Ordering Information**

Part Name	Quantity	Shipping Container
HAT2077R-EL-E	2500 pcs	Taping

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